

L Number	Hits	Search Text	DB	Time stamp
1	4	646891.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/21 02:20
2	2	6461891.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/21 02:20
3	2	6562662.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/21 02:37
4	2517261	chip die dice ic semiconductor (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/21 02:37
5	251584	(cap lid cover top) same (chip die dice ic semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/21 02:45
6	99254	(cap lid cover top) with (copper cu aluminum al)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/21 02:46
7	12697	((cap lid cover top) with (copper cu aluminum al)) same (chip die dice ic semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/21 02:46
8	557	((cap lid cover top) with (copper cu aluminum al)) same (chip die dice ic semiconductor (integrated adj circuit)) same epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/21 02:47